



SOT338-1

plastic shrink small outline package; 16 leads; body width 5.3 mm

8 February 2016

Package information

1. Package summary

Terminal position code	D (double)
Package type descriptive code	SSOP16
Package type industry code	SSOP16
Package style descriptive code	SSOP (shrink small outline package)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
JEDEC package outline code	MO-150
Mounting method type	S (surface mount)
Issue date	19-2-2003

Table 1. Package summary

Symbol	Parameter		Min	Typ	Nom	Max	Unit
D	package length		6	-	6.2	6.4	mm
E	package width		5.2	-	5.3	5.4	mm
A	seated height		[tbd]	-	2	2	mm
A ₂	package height		1.65	-	1.75	1.8	mm
n ₂	actual quantity of termination		-	-	16	-	



2. Package outline

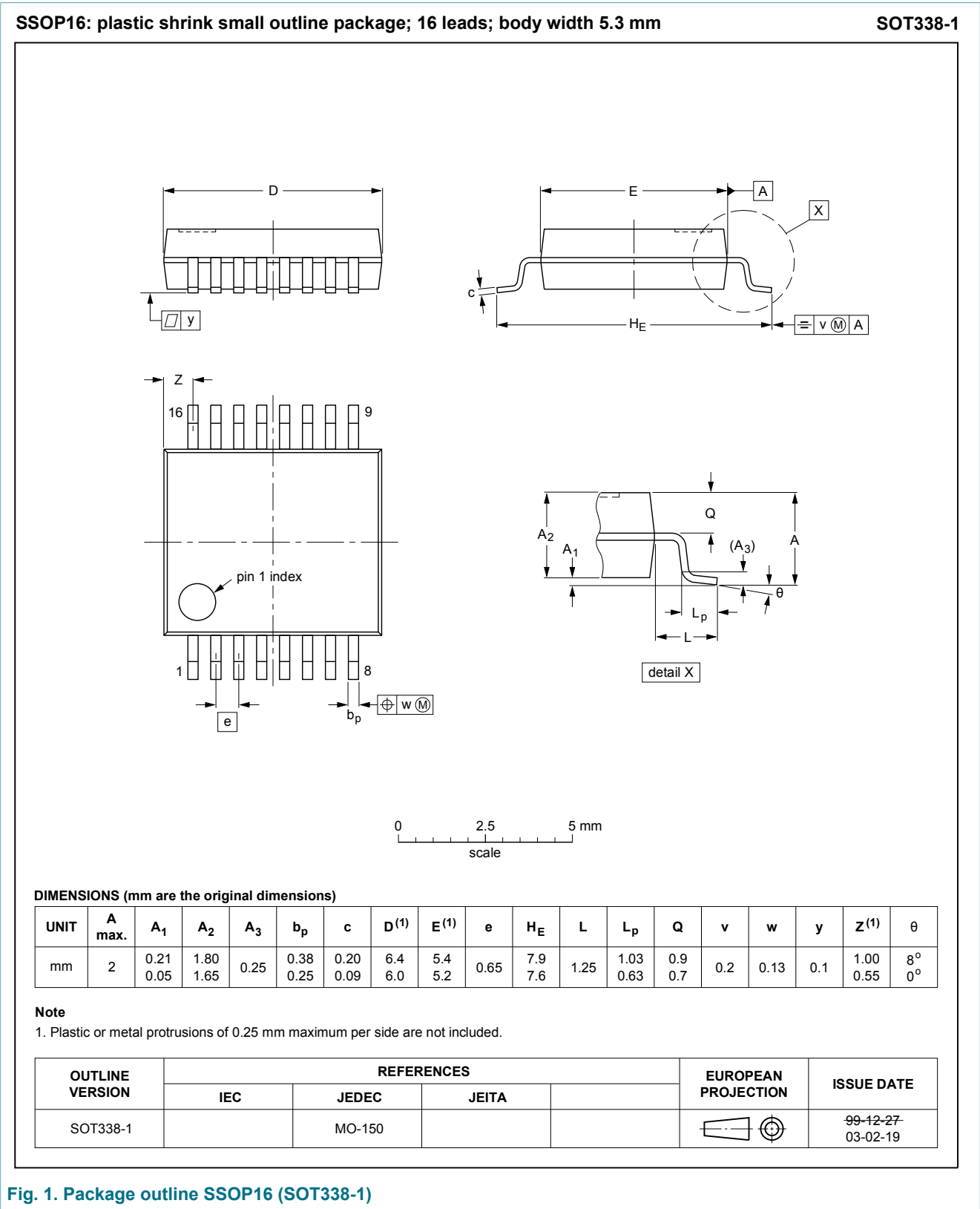


Fig. 1. Package outline SSOP16 (SOT338-1)

3. Soldering

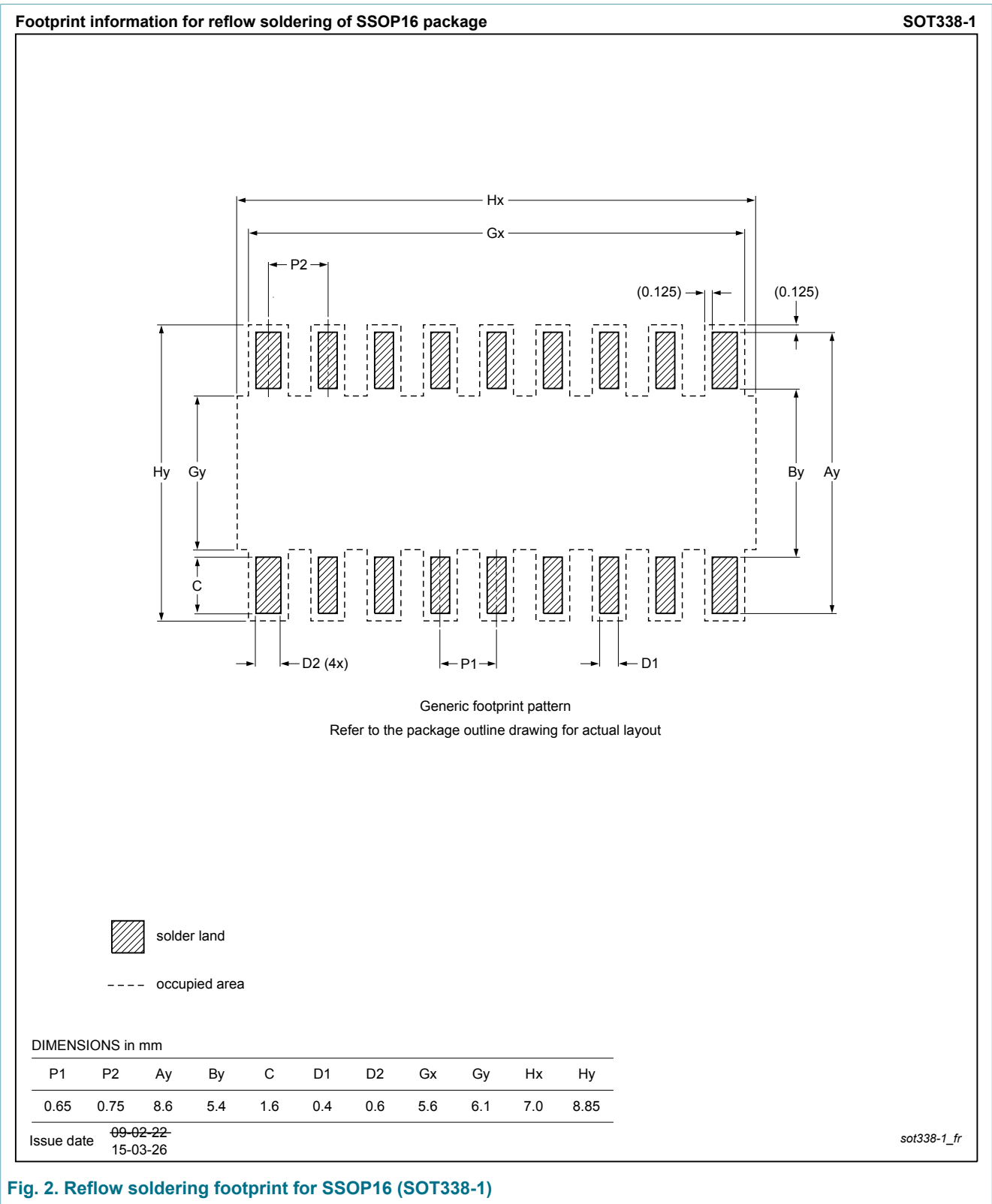
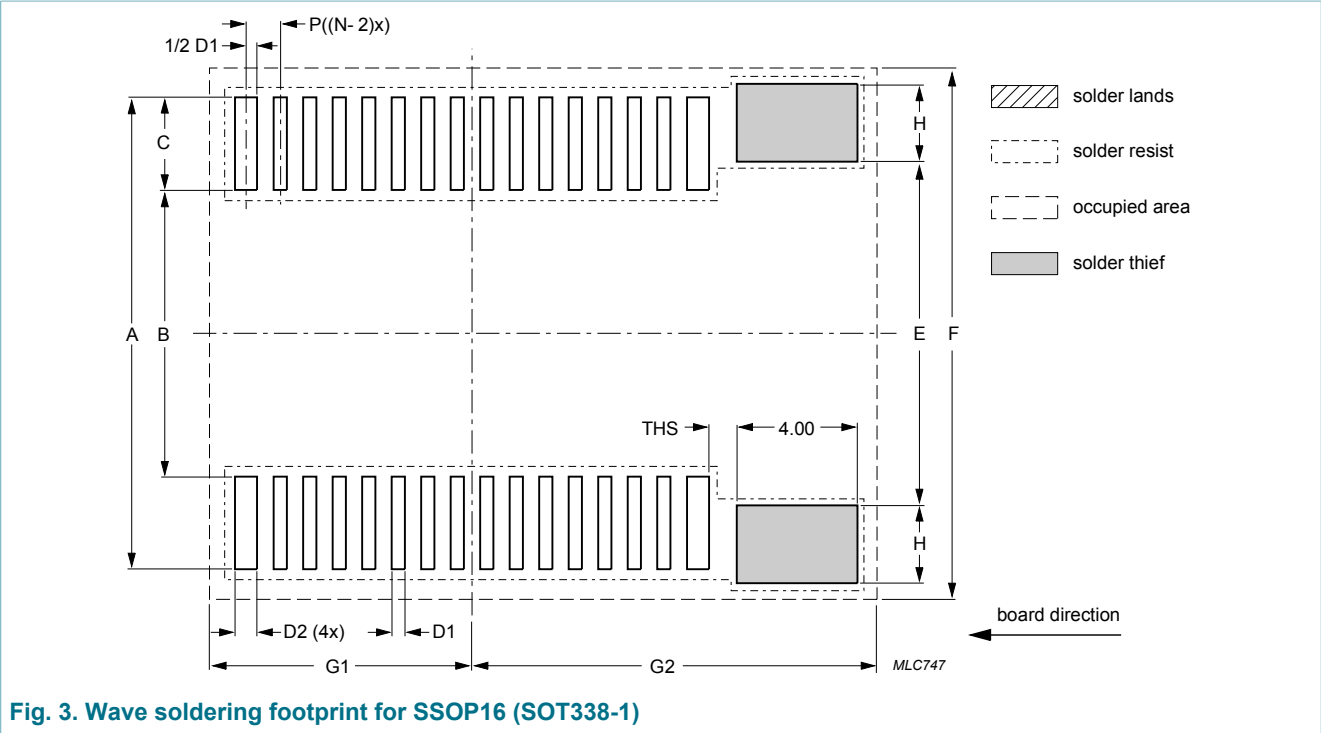


Fig. 2. Reflow soldering footprint for SSOP16 (SOT338-1)

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4. Legal information

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